

SOT1019-1

plastic low profile fine-pitch ball grid array package; 208 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA208
Package type industry code	LFBGA208
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-8-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	1.7	1.7	mm
A ₂	package height	1.2	-	1.35	1.35	mm
n ₂	actual quantity of termination	-	-	208	-	



2. Package outline

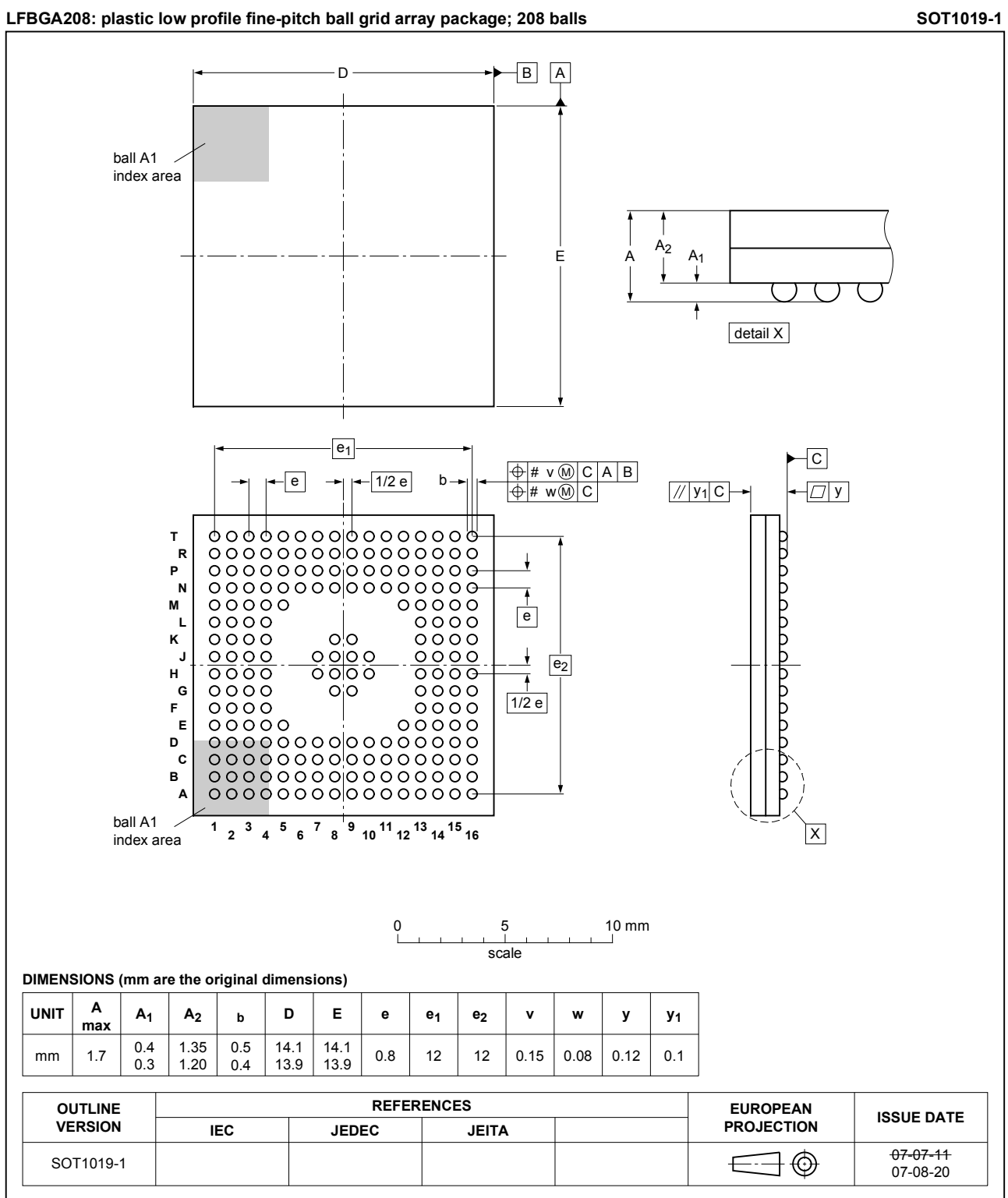


Fig. 1. Package outline LFPGA208 (SOT1019-1)

3. Legal information

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